

SKM 300 MLI 066 T



SEMITRANS[®] 5

Trench IGBT Modules

SKM 300 MLI 066 T

Target Data

Features

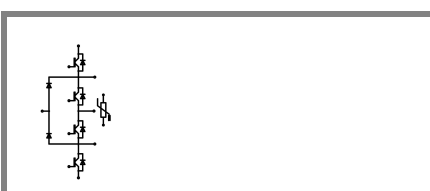
- Homogeneous Si
- Trench = Trenchgate technology
- $V_{CE(sat)}$ with positive temperature coefficient
- Integrated NTC temperature sensor

Typical Applications

- UPS
- 3 Level Inverter

Remarks

- Case temperature limited to $T_c = 125^\circ\text{C}$ max, recommended $T_{op} = -40..+150^\circ\text{C}$



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Absolute Maximum Ratings		$T_{case} = 25^\circ\text{C}$, unless otherwise specified		
Symbol	Conditions	Values		Units
IGBT				
V_{CES}	$T_j = 25^\circ\text{C}$	600		V
I_C	$T_j = 175^\circ\text{C}$	$T_c = 25^\circ\text{C}$	340	A
		$T_c = 80^\circ\text{C}$	255	A
I_{CRM}	$I_{CRM} = 2 \times I_{Cnom}$	600		A
V_{GES}		± 20		V
t_{psc}	$V_{CC} = 360\text{ V}; V_{GE} \leq 15\text{ V}; T_j = 150^\circ\text{C}$ $V_{CES} < 600\text{ V}$	6		μs
Inverse Diode				
I_F	$T_j = 150^\circ\text{C}$	$T_c = 25^\circ\text{C}$	324	A
		$T_c = 80^\circ\text{C}$	211	A
I_{FRM}	$I_{FRM} = 2 \times I_{Fnom}$	420		A
I_{FSM}	$t_p = 10\text{ ms}; \text{half sine wave } T_j = 150^\circ\text{C}$	2100		A
Freewheeling Diode				
I_F	$T_j = 150^\circ\text{C}$	$T_c = 25^\circ\text{C}$	324	A
		$T_c = 80^\circ\text{C}$	211	A
I_{FRM}	$I_{FRM} = 2 \times I_{Fnom}$	420		A
I_{FSM}	$t_p = 10\text{ ms}; \text{half sine wave } T_j = 150^\circ\text{C}$	2100		A
Module				
$I_{t(RMS)}$		500		A
T_{vj}		- 40 ... + 175		$^\circ\text{C}$
T_{stg}		- 40 ... + 125		$^\circ\text{C}$
V_{isol}	AC, 1 min.	2500		V

Characteristics		$T_{case} = 25^\circ\text{C}$, unless otherwise specified			
Symbol	Conditions	min.	typ.	max.	Units
IGBT					
$V_{GE(th)}$	$V_{GE} = V_{CE}, I_C = 4,8\text{ mA}$	5	5,8	6,5	V
I_{CES}	$V_{GE} = 0\text{ V}, V_{CE} = V_{CES} T_j = 25^\circ\text{C}$			0,015	mA
I_{GES}	$V_{CE} = 0\text{ V}, V_{GE} = 20\text{ V } T_j = 25^\circ\text{C}$			1200	nA
V_{CE0}		$T_j = 25^\circ\text{C}$	0,9	1	V
		$T_j = 150^\circ\text{C}$	0,85	0,9	V
r_{CE}	$V_{GE} = 15\text{ V}$	$T_j = 25^\circ\text{C}$	1,8	3	$\text{m}\Omega$
		$T_j = 150^\circ\text{C}$	2,7	3,8	$\text{m}\Omega$
$V_{CE(sat)}$	$I_{Cnom} = 300\text{ A}, V_{GE} = 15\text{ V}$	$T_j = 25^\circ\text{C}_{chiplev.}$	1,45	1,9	V
		$T_j = 150^\circ\text{C}_{chiplev.}$	1,7	2,1	V
C_{ies}	$V_{CE} = 25, V_{GE} = 0\text{ V } f = 1\text{ MHz}$		18,4		nF
C_{oes}			1,14		nF
C_{res}			0,54		nF
Q_G	$V_{GE} = -15\text{V}...+15\text{V}$		3900		nC
R_{Gint}	$T_j = ^\circ\text{C}$		1		Ω
$t_{d(on)}$	$R_{Gon} = 2,2\ \Omega$ $di/dt = 3400\text{ A}/\mu\text{s}$	$V_{CC} = 300\text{V}$ $I_C = 300\text{A}$	140		ns
t_r			89		ns
E_{on}	$R_{Goff} = 2,2\ \Omega$ $di/dt = 3400\text{ A}/\mu\text{s}$	$T_j = 125^\circ\text{C}$ $V_{GE} = -15\text{V}/+15\text{V}$	3,5		mJ
$t_{d(off)}$			433		ns
t_f			116		ns
E_{off}			10,1		mJ
$R_{th(j-c)}$	per IGBT		0,2		K/W



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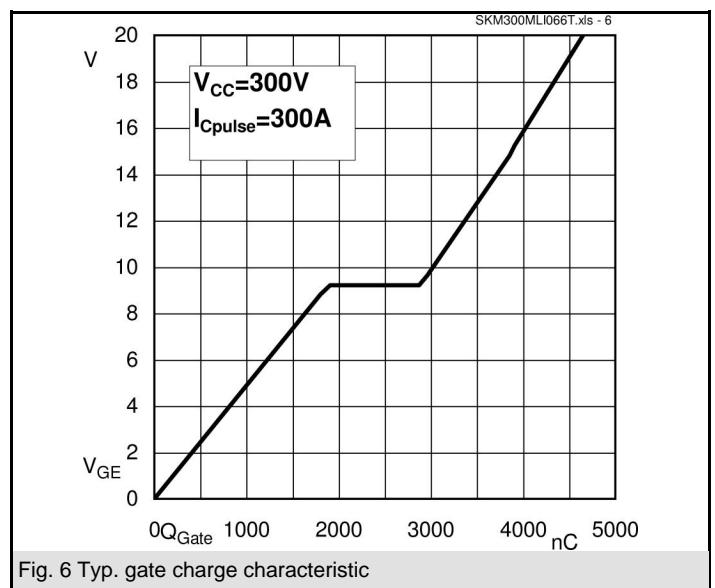
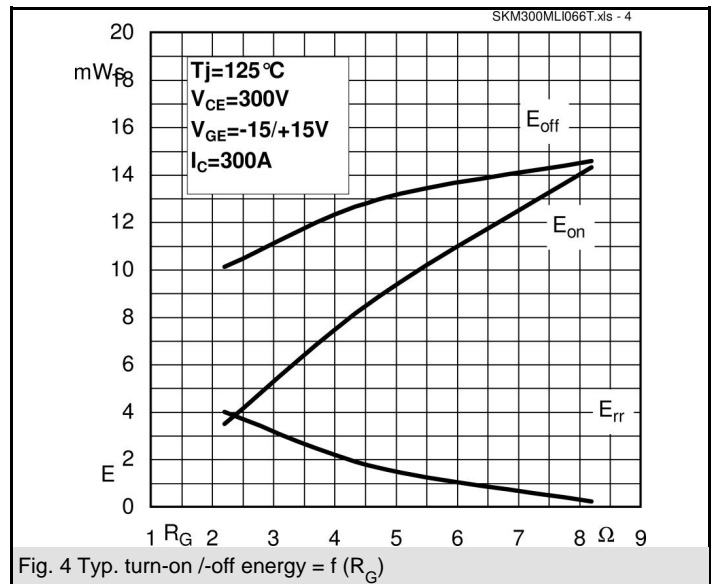
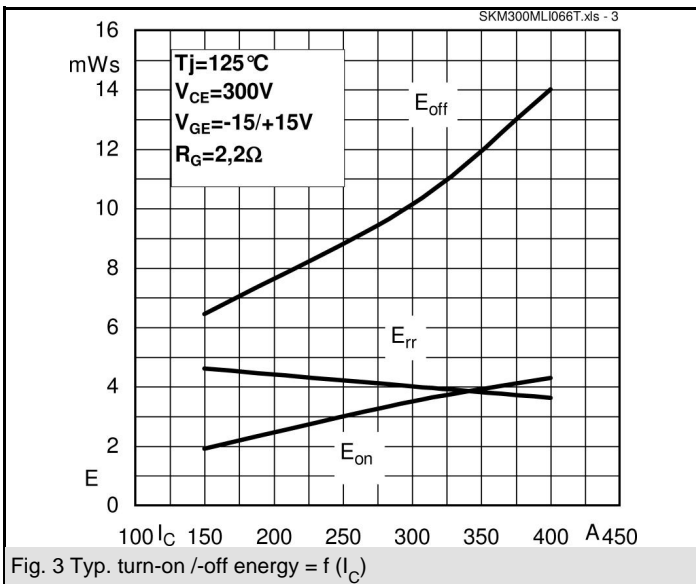
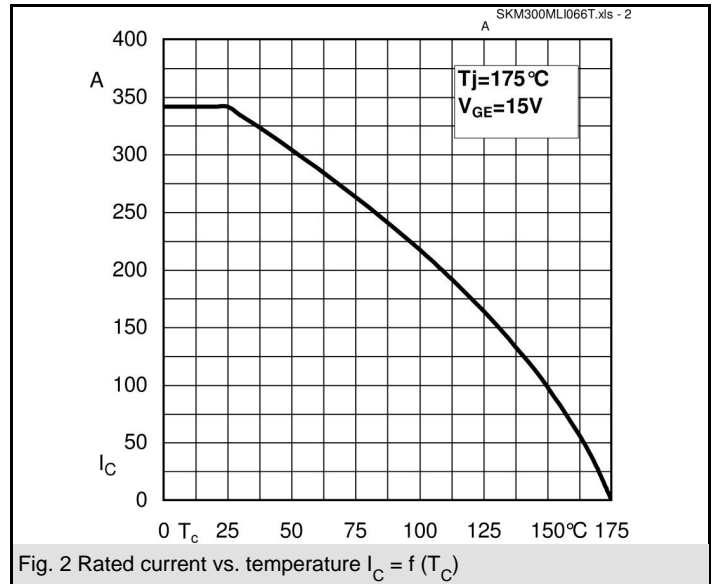
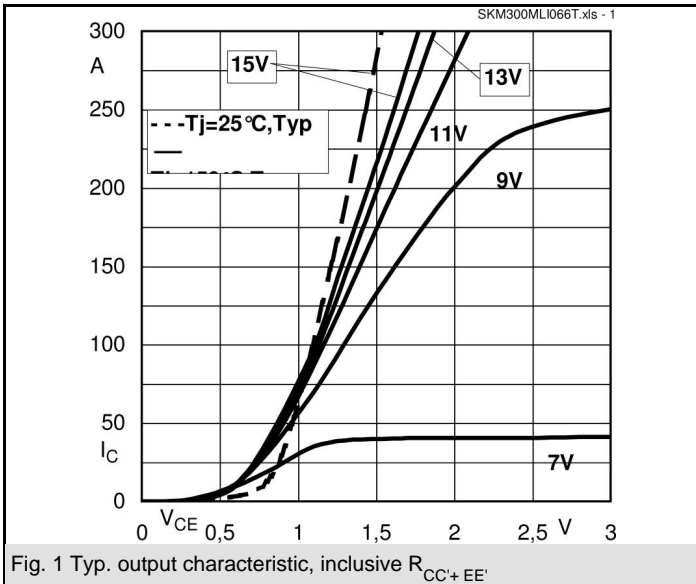


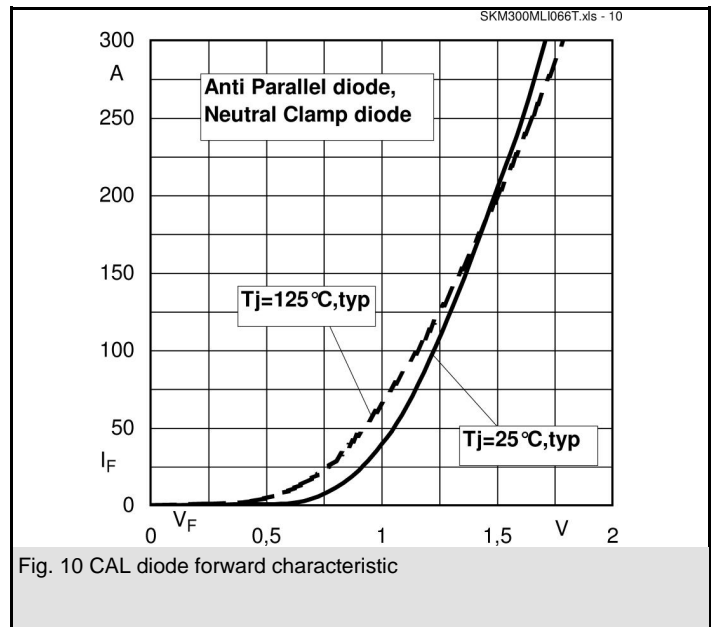
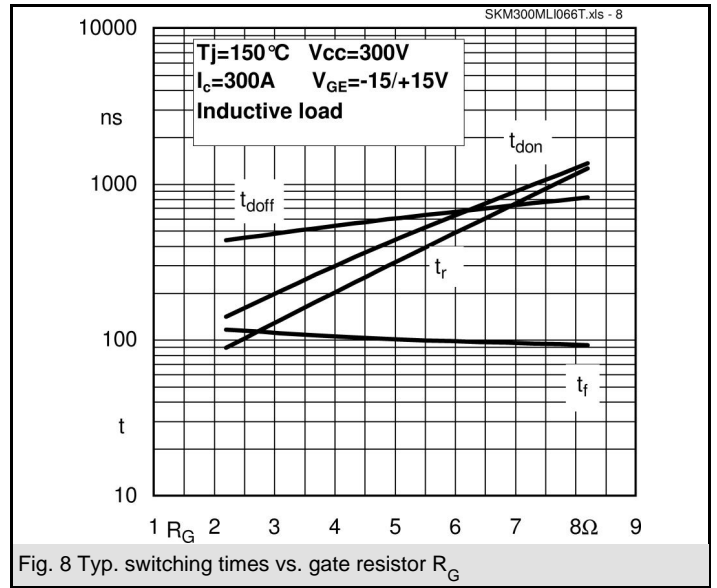
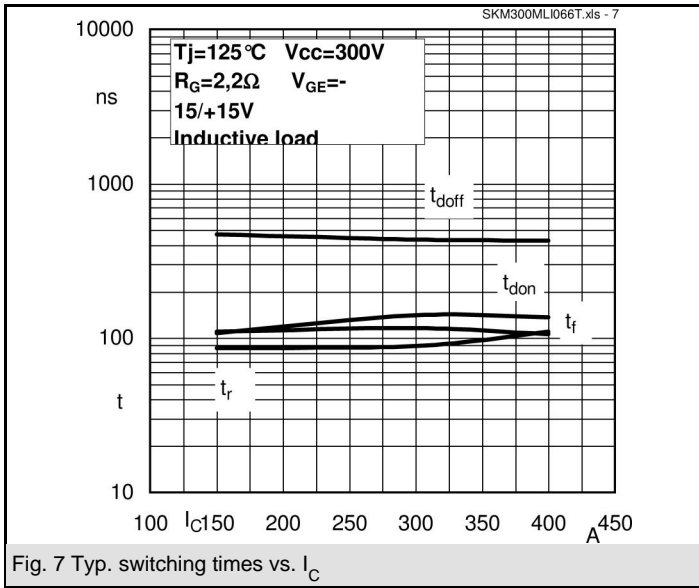
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Characteristics				min.	typ.	max.	Units
Symbol	Conditions						
Inverse Diode							
$V_F = V_{EC}$	$I_{Fnom} = 245\text{ A}; V_{GE} = 0\text{ V}$	$T_j = 25^\circ\text{C}_{chiplev.}$		1,35	1,6		V
		$T_j = 125^\circ\text{C}_{chiplev.}$		1,35	1,6		V
V_{F0}		$T_j = 25^\circ\text{C}$		1	1,1		V
		$T_j = 125^\circ\text{C}$		0,9	1		V
r_F		$T_j = 25^\circ\text{C}$		1,42	2		mΩ
		$T_j = 125^\circ\text{C}$		1,8	2,4		mΩ
I_{RRM}	$I_F = 245\text{ A}$	$T_j = 125^\circ\text{C}$					A
Q_{rr}							μC
E_{rr}	$V_{GE} = -8\text{ V}; V_{CC} = 300\text{ V}$						mJ
$R_{th(j-c)D}$	per diode			0,28			K/W
Free-wheeling diode (Neutral Clamp Diode)							
$V_F = V_{EC}$	$I_{Fnom} = 245\text{ A}; V_{GE} = 0\text{ V}$	$T_j = 25^\circ\text{C}_{chiplev.}$		1,35	1,6		V
		$T_j = 125^\circ\text{C}_{chiplev.}$		1,35	1,6		V
V_{F0}		$T_j = 25^\circ\text{C}$		1	1,1		V
		$T_j = 125^\circ\text{C}$		0,9	1		V
r_F		$T_j = 25^\circ\text{C}$		1,42	2		V
		$T_j = 125^\circ\text{C}$		1,8	2,4		V
I_{RRM}	$I_F = 300\text{ A}$	$T_j = 125^\circ\text{C}$		194			A
Q_{rr}	$di/dt = 3400\text{ A}/\mu\text{s}$			13			μC
E_{rr}	$V_{GE} = 0\text{ V}; V_{CC} = 300\text{ V}$			4			mJ
$R_{th(j-c)FD}$	per diode			0,28			K/W
M_s	to heat sink M6			3	5		Nm
M_t	to terminals M6			2,5	5		Nm
w					310		g
Temperature sensor							
R_{100}	$T_s = 100^\circ\text{C} (R_{25} = 5\text{k}\Omega)$			493±5%			Ω
							K

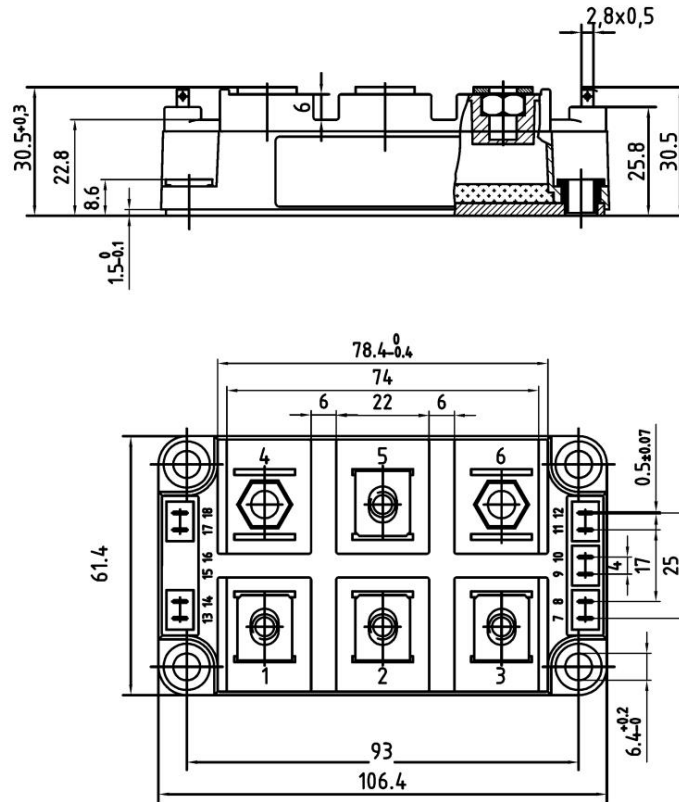
This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.

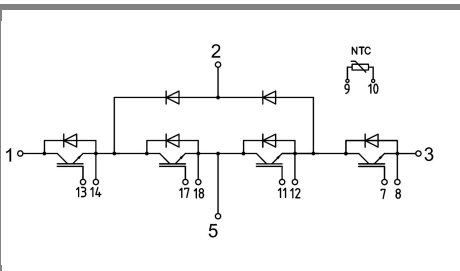




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Case D60



MLI-T

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